**Product data sheet** 

## 1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in a SOT186A (TO-220F) "full pack" plastic package intended for use in applications requiring high bidirectional blocking voltage and high current surge capability with high thermal cycling performance.

#### 2. Features and benefits

- · High bidirectional blocking voltage capability
- · High current surge capability
- · High thermal cycling performance
- Isolated mounting base package
- Planar passivated for voltage ruggedness and reliability

### 3. Applications

- Capacitive Discharge Ignition (CDI)
- Crowbar protection
- · Inrush protection
- Motor control
- Voltage regulation

#### 4. Quick reference data

Table 1. Quick reference data

| Symbol              | Parameter                                | Conditions   | Min | Тур | Max | Unit |
|---------------------|--|--|-----|-----|-----|------|
| $V_{RRM}$           | repetitive peak reverse voltage          |  | -   | -   | 800 | V    |
| I <sub>T(AV)</sub>  | average on-state current                 | half sine wave; T <sub>h</sub> ≤ 69 °C   | -   | -   | 7.5 | А    |
| I <sub>T(RMS)</sub> | RMS on-state current                     | half sine wave; $T_h \le 69 ^{\circ}\text{C}$ ; $\overline{\text{Fig. 1}}$ ; $\overline{\text{Fig. 2}}$ ; $\overline{\text{Fig. 3}}$ | -   | -   | 12  | А    |
| I <sub>TSM</sub>    | non-repetitive peak on-<br>state current | half sine wave; $T_{j(init)}$ = 25 °C;<br>$t_p$ = 10 ms; Fig. 4; Fig. 5  | -   | -   | 120 | A    |
|                     |  | half sine wave; $T_{j(init)}$ = 25 °C;<br>$t_p$ = 8.3 ms   | -   | -   | 132 | А    |
| Tj                  | junction temperature                     |  | -   | -   | 125 | °C   |
| Static chara        | acteristics                              |  |     |     |     |      |
| I <sub>GT</sub>     | gate trigger current                     | $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 7$   | -   | 2   | 15  | mA   |
| Dynamic ch          | naracteristics                           |  |     |     |     |      |

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| Symbol              | Parameter                         | Conditions  | Min | Тур  | Max | Unit |
|---------------------|-----------------------------------|---|-----|------|-----|------|
| dV <sub>D</sub> /dt | rate of rise of off-state voltage | $V_{DM}$ = 536 V; $T_j$ = 125 °C; $R_{GK}$ = 100 Ω; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit; Fig. 12 | 200 | 1000 | -   | V/µs |
|                     |                                   | $V_{DM}$ = 536 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; Fig. 12                                      | 50  | 130  | -   | V/µs |

# 5. Pinning information

#### **Table 2. Pinning information**

| 1 K cathode 2 A anode 3 G gate mb G sym037 | Pin | Symbol | Description             | Simplified outline | Graphic symbol                                    |
|--|-----|--------|-------------------------|--------------------|---|
| 3 G gate                                   | 1   | K      | cathode                 | mb                 | A <del>-                                   </del> |
| 3 G gate                                   | 2   | Α      | anode                   |                    | _   |
| mb n.c. mounting base; isolated            | 3   | G      | gate                    |                    | symosi  |
| 1 2 3<br>TO-220F (SOT186A)                 | mb  | n.c.   | mounting base; isolated | · = *              |   |

# 6. Ordering information

#### **Table 3. Ordering information**

| Type number | Package |   |         |  |  |  |
|-------------|---------|---|---------|--|--|--|
|             | Name    | Description   | Version |  |  |  |
| BT151X-800R | TO-220F | plastic single-ended package; isolated heatsink mounted; 1 mounting hole; 3-lead TO-220 "full pack" | SOT186A |  |  |  |

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# 7. Limiting values

#### **Table 4. Limiting values**

In accordance with the Absolute Maximum Rating System (IEC 60134).

| Symbol              | Parameter                                | Conditions  | Min | Max | Unit |
|---------------------|--|---|-----|-----|------|
| $V_{DRM}$           | repetitive peak off-state voltage        |   | -   | 800 | V    |
| $V_{RRM}$           | repetitive peak reverse voltage          |   | -   | 800 | V    |
| I <sub>T(AV)</sub>  | average on-state current                 | half sine wave; T <sub>h</sub> ≤ 69 °C  | -   | 7.5 | Α    |
| I <sub>T(RMS)</sub> | RMS on-state current                     | half sine wave; $T_h \le 69 ^{\circ}\text{C}$ ; Fig. 1; Fig. 2; Fig. 3                    | -   | 12  | Α    |
| I <sub>TSM</sub>    | non-repetitive peak on-<br>state current | half sine wave; $T_{j(init)} = 25 \text{ °C}$ ; $t_p = 10 \text{ ms}$ ;<br>Fig. 4; Fig. 5 | -   | 120 | Α    |
|                     |  | half sine wave; T <sub>j(init)</sub> = 25 °C; t <sub>p</sub> = 8.3 ms                     | -   | 132 | Α    |
| l <sup>2</sup> t    | I <sup>2</sup> t for fusing              | t <sub>p</sub> = 10 ms; SIN   | -   | 72  | A²s  |
| dl <sub>T</sub> /dt | rate of rise of on-state current         | I <sub>G</sub> = 30 mA  | -   | 50  | A/µs |
| I <sub>GM</sub>     | peak gate current                        |   | -   | 2   | Α    |
| $V_{RGM}$           | peak reverse gate voltage                |   | -   | 5   | V    |
| P <sub>GM</sub>     | peak gate power                          |   | -   | 5   | W    |
| P <sub>G(AV)</sub>  | average gate power                       | over any 20 ms period   | -   | 0.5 | W    |
| T <sub>stg</sub>    | storage temperature                      |   | -40 | 150 | °C   |
| T <sub>j</sub>      | junction temperature                     |   | -   | 125 | °C   |

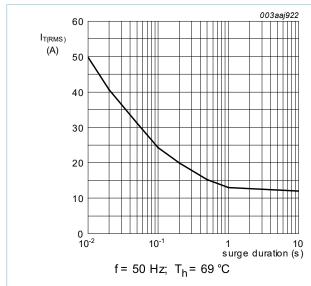


Fig. 1. RMS on-state current as a function of surge duration; maximum values

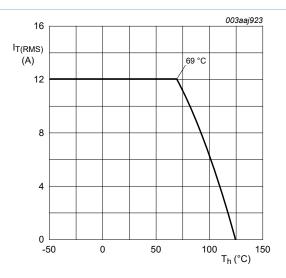


Fig. 2. RMS on-state current as a function of heatsink temperature; maximum values

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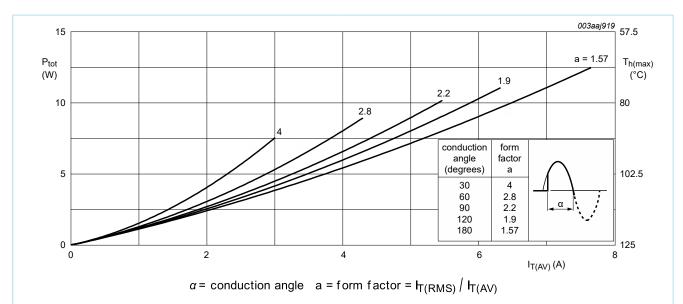


Fig. 3. Total power dissipation as a function of average on-state current; maximum values

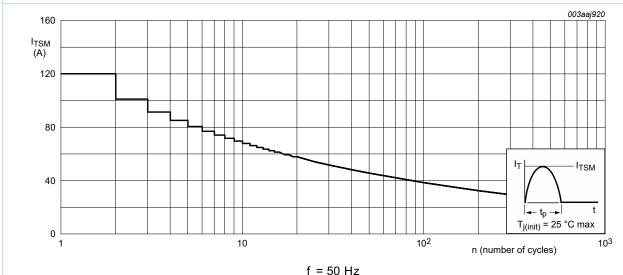
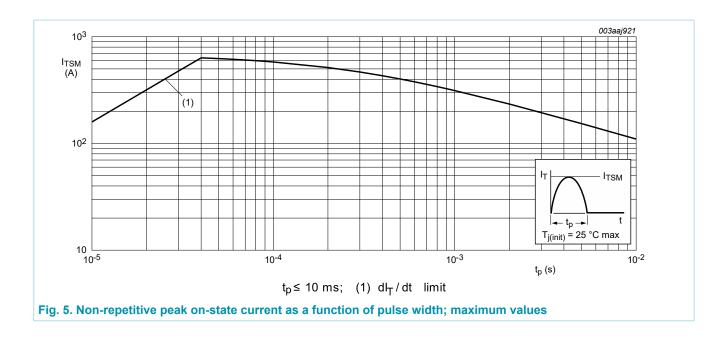


Fig. 4. Non-repetitive peak on-state current as a function of the number of sinusoidal current cycles; maximum values

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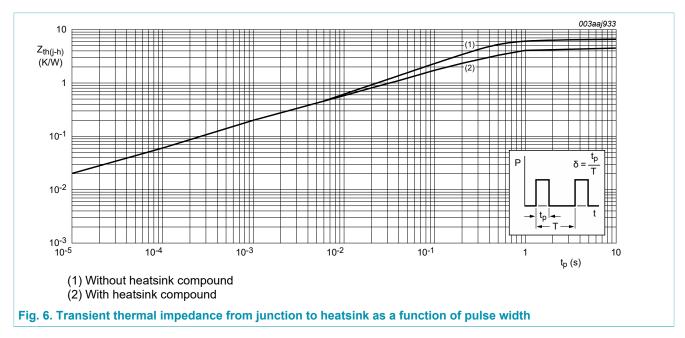
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### 8. Thermal characteristics

**Table 5. Thermal characteristics** 

| Symbol               | Parameter  | Conditions                        | Min | Тур | Max | Unit |
|----------------------|--|-----------------------------------|-----|-----|-----|------|
| R <sub>th(j-h)</sub> | thermal resistance<br>from junction to<br>heatsink         | with heatsink compound; Fig. 6    | -   | -   | 4.5 | K/W  |
|                      |  | without heatsink compound; Fig. 6 | -   | -   | 6.5 | K/W  |
| R <sub>th(j-a)</sub> | thermal resistance<br>from junction to<br>ambient free air | in free air                       | -   | 55  | -   | K/W  |



### 9. Isolation characteristics

**Table 6. Isolation characteristics** 

| Symbol                 | Parameter             | Conditions   | Min | Тур | Max  | Unit |
|------------------------|-----------------------|--|-----|-----|------|------|
| V <sub>isol(RMS)</sub> | RMS isolation voltage | from all terminals to external heatsink; sinusoidal waveform; clean and dust free; 50 Hz $\leq$ f $\leq$ 60 Hz; RH $\leq$ 65 %; T <sub>h</sub> = 25 °C | -   | -   | 2500 | V    |
| C <sub>isol</sub>      | isolation capacitance | from anode to external heatsink;<br>f = 1 MHz; T <sub>h</sub> = 25 °C  | -   | 10  | -    | pF   |

### 10. Characteristics

**Table 7. Characteristics** 

| Symbol              | Parameter                         | Conditions  | Min  | Тур  | Max  | Unit |
|---------------------|-----------------------------------|---|------|------|------|------|
| Static char         | racteristics                      |   |      |      |      |      |
| $I_{GT}$            | gate trigger current              | $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C}; Fig. 7$  | -    | 2    | 15   | mA   |
| IL                  | latching current                  | $V_D = 12 \text{ V}; I_G = 0.1 \text{ A}; T_j = 25 ^{\circ}\text{C}; Fig. 8$  | -    | 10   | 40   | mA   |
| I <sub>H</sub>      | holding current                   | V <sub>D</sub> = 12 V; T <sub>j</sub> = 25 °C; <u>Fig. 9</u>  | -    | 7    | 20   | mA   |
| $V_{T}$             | on-state voltage                  | I <sub>T</sub> = 23 A; T <sub>j</sub> = 25 °C; <u>Fig. 10</u>   | -    | 1.4  | 1.75 | V    |
| $V_{GT}$            | gate trigger voltage              | $V_D = 12 \text{ V}; I_T = 0.1 \text{ A}; T_j = 25 \text{ °C};$<br>Fig. 11  | -    | 0.6  | 1    | V    |
|                     |                                   | $V_D = 800 \text{ V}; I_T = 0.1 \text{ A}; T_j = 125 \text{ °C};$<br>Fig. 11  | 0.25 | 0.4  | -    | V    |
| I <sub>D</sub>      | off-state current                 | V <sub>D</sub> = 800 V; T <sub>j</sub> = 125 °C   | -    | 0.1  | 0.5  | mA   |
| I <sub>R</sub>      | reverse current                   | V <sub>R</sub> = 800 V; T <sub>j</sub> = 125 °C   | -    | 0.1  | 0.5  | mA   |
| Dynamic c           | haracteristics                    |   |      |      |      |      |
| dV <sub>D</sub> /dt | rate of rise of off-state voltage | $V_{DM}$ = 536 V; $T_j$ = 125 °C; $R_{GK}$ = 100 Ω; $(V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; gate open circuit; Fig. 12  | 200  | 1000 | -    | V/µs |
|                     |                                   | $V_{DM}$ = 536 V; $T_j$ = 125 °C; ( $V_{DM}$ = 67% of $V_{DRM}$ ); exponential waveform; Fig. 12  | 50   | 130  | -    | V/µs |
| t <sub>gt</sub>     | gate-controlled turn-on time      | $I_{TM}$ = 40 A; $V_D$ = 800 V; $I_G$ = 100 mA; $dI_G/dt$ = 5 A/ $\mu$ s; $T_j$ = 25 °C   | -    | 2    | -    | μs   |
| t <sub>q</sub>      | commutated turn-off time          | $V_{DM} = 536 \text{ V}; T_j = 125 \text{ °C}; I_{TM} = 20 \text{ A}; V_R = 25 \text{ V}; (dI_T/dt)_M = 30 \text{ A/µs}; dV_D/dt = 50 \text{ V/µs}; R_{GK(ext)} = 100 \Omega; (V_{DM} = 67\% \text{ of V}_{DRM})$ | -    | 70   | -    | μs   |

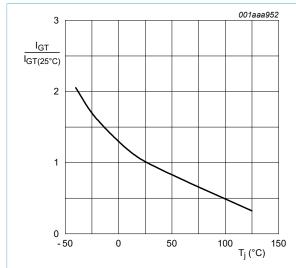


Fig. 7. Normalized gate trigger current as a function of junction temperature

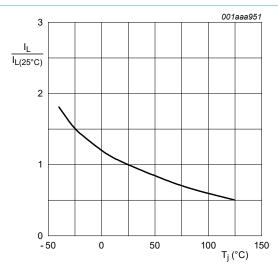


Fig. 8. Normalized latching current as a function of junction temperature

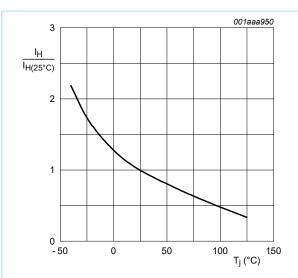
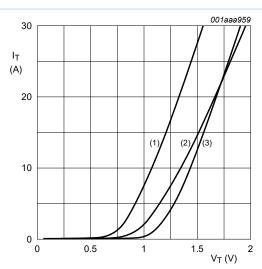


Fig. 9. Normalized holding current as a function of junction temperature



 $V_{o}$  = 1.06 V;  $R_{s}$  = 0.0304  $\Omega$  (1)  $T_{j}$  = 125 °C; typical values (2)  $T_{j}$  = 125 °C; maximum values

(3)  $T_j = 125$  °C; maximum values

Fig. 10. On-state current as a function of on-state voltage

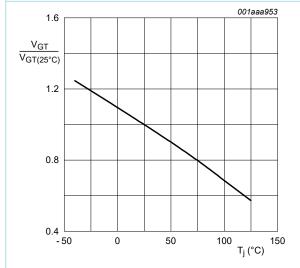
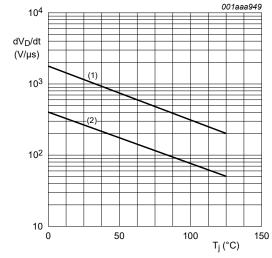


Fig. 11. Normalized gate trigger voltage as a function of junction temperature



(1)  $R_{GK} = 100 \Omega$ ; (2) gate open circuit

Fig. 12. Critical rate of rise of off-state voltage as a function of junction temperature; minimum values

## 11. Package outline

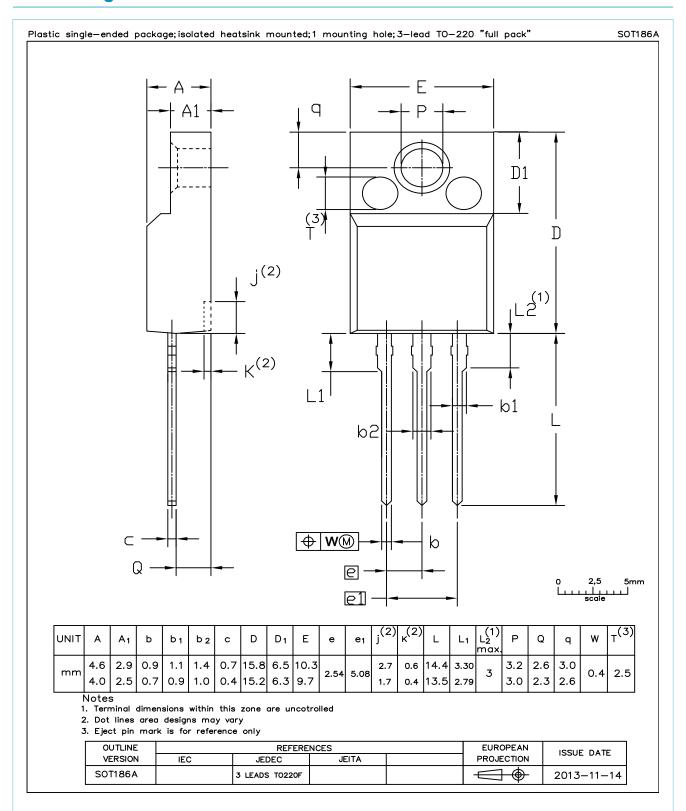


Fig. 13. Package outline TO-220F (SOT186A)

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## 12. Legal information

#### **Data sheet status**

| Document status [1][2]               | Product status [3] | Definition  |
|--------------------------------------|--------------------|---|
| Objective<br>[short] data<br>sheet   | Development        | This document contains data from the objective specification for product development. |
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